

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 61188957
 PUBLICATION DATE : 22-08-86

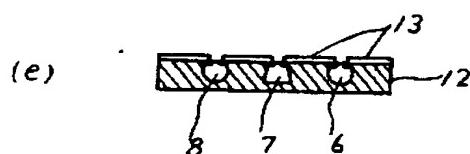
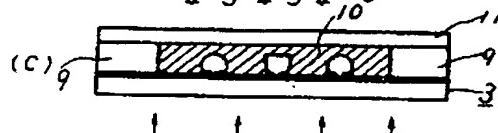
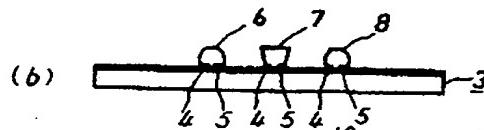
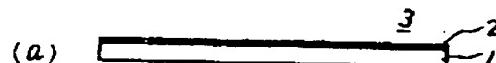
APPLICATION DATE : 18-02-85
 APPLICATION NUMBER : 60028243

APPLICANT : TOSHIBA CORP;

INVENTOR : OUCHI MASAYUKI;

INT.CL. : H01L 25/04 H01L 21/56 H05K 3/32

TITLE : MANUFACTURE OF CIRCUIT MODULE



ABSTRACT : PURPOSE: To obtain a circuit module of the same extremely thin degree as the thickness of a chip type electronic parts by mounting in the shape that the parts are effectively buried in a substrate made of cured resin.

CONSTITUTION: A silicone resin film 2 is obtained on a glass plate 1, gelled to impart adhesive and mold releasing properties to the surface as a support 3. Electrodes 4, 5 sides are disposed at the prescribed positions on the support 3 of drawn trapezoidal or semicircular-sectional cylindrical chip type electronic parts 6-8. Spacers 9 made of Teflon are disposed, ultraviolet curable resin 10 is molded around the parts 6-8 on the support 3 in this state, a flat plate 11 made, for example, Teflon is coated thereon, and ultraviolet ray is emitted to cure the resin 10. Then, the support 3, the plate 11 and the spacers 9 are separated to obtain the parts 6-8 buried in a substrate 12. Then, silver paste is screen printed to form a desired conductor pattern 13.

COPYRIGHT: (C)1986,JPO&Japio